

SE2101

**P-Channel Enhancement-Mode MOSFET**

Revision: A

**General Description**

This type is P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology. This device particularly suits low voltage applications, especially for battery powered circuits.

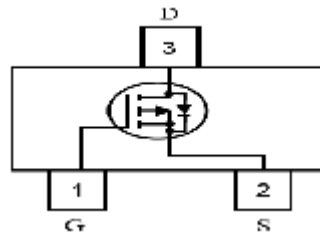
**Features**

For a single MOSFET

- $V_{DS} = -20V$
- $I_D = -0.9A$
- $R_{DS(ON)} = 280m\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)} = 370m\Omega @ V_{GS} = -2.5V$

**Pin configurations**

See Diagram below



SOT-23

**Absolute Maximum Ratings**

Parameter		Symbol	Rating	Units
Drain-Source Voltage		$V_{DS}$	-20	V
Gate-Source Voltage		$V_{GS}$	$\pm 12$	V
Drain Current	Continuous	$I_D$	-0.9	A
	Pulsed		-3	
Total Power Dissipation	@TA=25°C	$P_D$	250	mW
Operating Junction Temperature Range		$T_J$	-55 to 150	°C

## SE2101

Electrical Characteristics (T <sub>J</sub> =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS (Note 2)</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA, V <sub>GS</sub> =0 V	-20			V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = -16V, V <sub>GS</sub> =0V			-1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = 12V			10	μA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =-250μA	-0.35	-0.6	-1	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-1A		280	300	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-0.5A		370	400	
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-6V, f=200KHz		200		pF
C <sub>oss</sub>	Output Capacitance			80		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			150		pF
<b>SWITCHING PARAMETERS</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-6V, R <sub>GEN</sub> =6Ω, I <sub>D</sub> =-1A		10		ns
t <sub>d(off)</sub>	Turn-Off Delay Time			19		ns
t <sub>d(r)</sub>	Turn-On Rise Time			62		ns
t <sub>d(f)</sub>	Turn-Off Fall Time			18		ns
<b>Thermal Resistance</b>						
Symbol	Parameter		Typ	Max		Units
R <sub>θJC</sub>	Junction to Case		6.9	8		°C/W
R <sub>θJA</sub>	Junction to Ambient (t ≅ 10s)		52	62.5		°C/W

Typical Characteristics

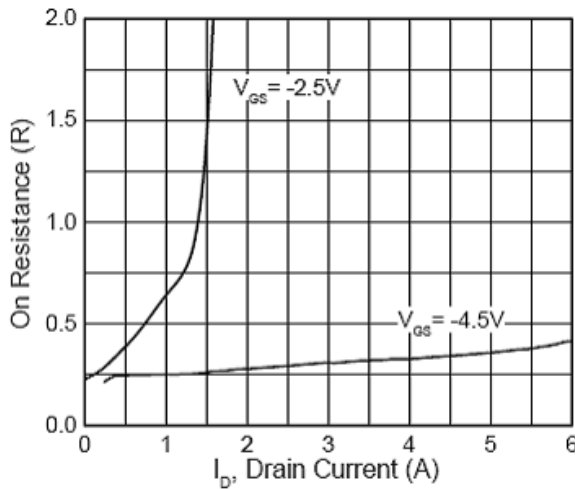


Figure 3. On Resistance VS  $I_D$

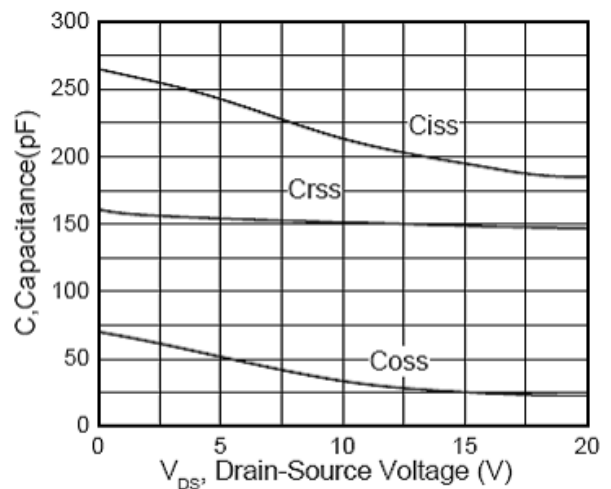


Figure 4. Capacitance

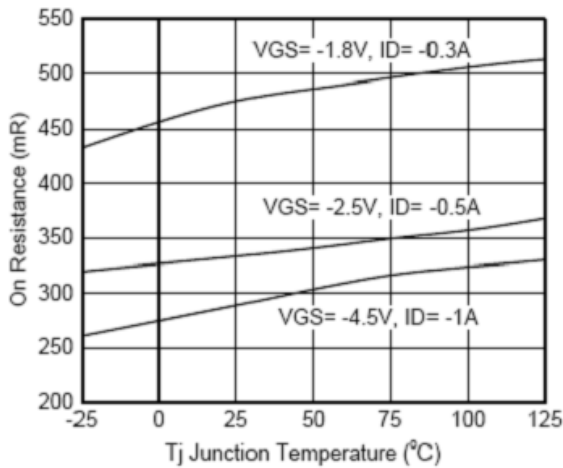


Figure 5. On resistance VS Temperature

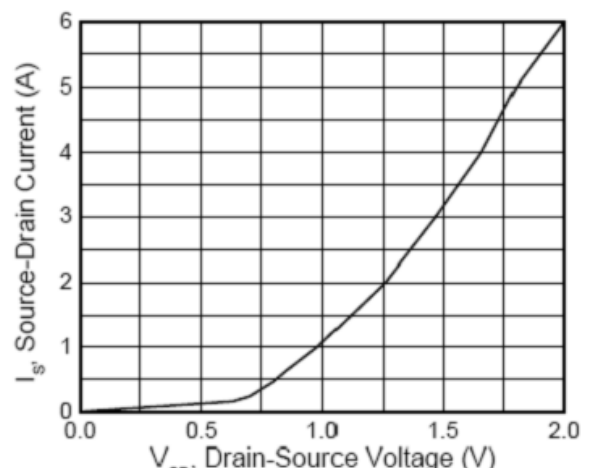


Figure 6.  $V_{SD}$  VS  $I_S$

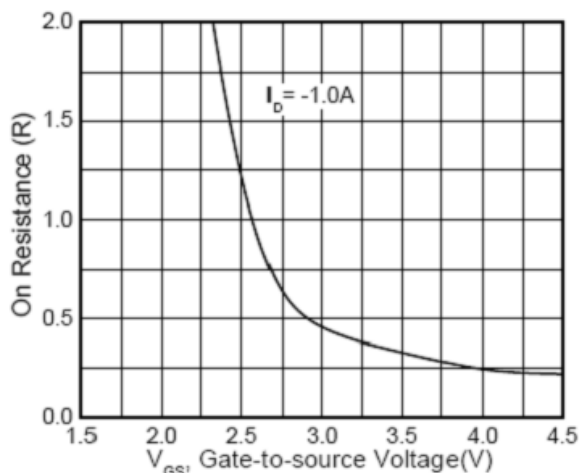


Figure 7. On Resistance VS  $V_{GS}$

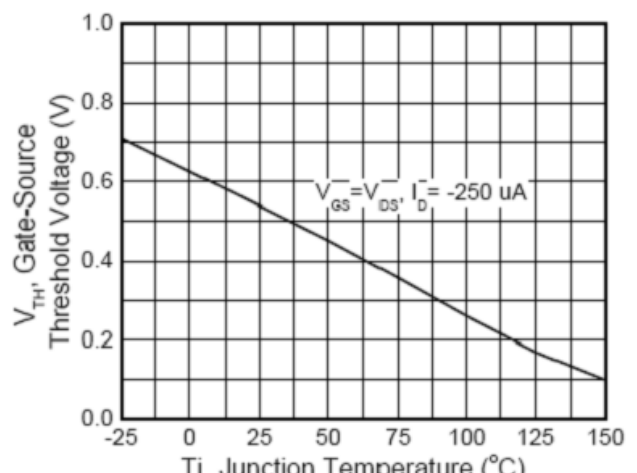
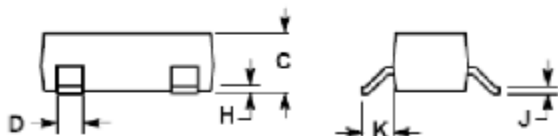
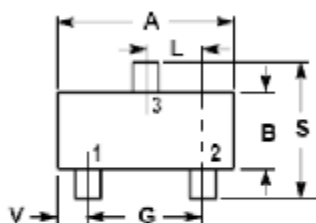


Figure 8. Gate Threshold Vs. Temperature

# SE2101

## Package Outline Dimension

### SOT-23



#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M,1982
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.1102	0.1197	2.80	3.04
B	0.0472	0.0551	1.20	1.40
C	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
H	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
V	0.0177	0.0236	0.45	0.60